# MGV2520122R2M-10

### PHYSICAL DIMENSIONS:

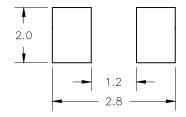
A  $2.50 \pm 0.20$ 

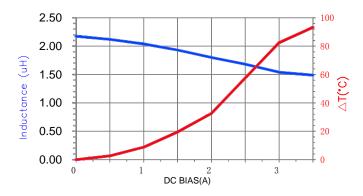
B  $2.00 \pm 0.20$ 

C 1.20 Max.

 $D = 0.60 \pm 0.30$ 

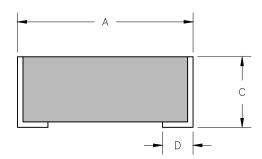
#### LAND PATTERNS FOR REFLOW SOLDERING



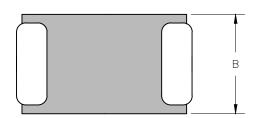


## ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max
INDUCTANCE (uH) L @ 1MHz/1mA ±20%	1.76	2.20	2.64
DCR $(\Omega)$		0.085	0.098
Saturation Current Isat (A)		3.00	2.73
Heating Current Irms (A)		2.27	2.06







#### NOTES:

- 1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. OPERATING TEMPERATURE RANGE:  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ .
- 4. STORAGE TEMPERATURE RANGE: -40°C ~ +85°C .
- 5. ISat MEANS THAT MAX DC CURRENT WILL CAUSE A PROXIMATELY 30% INDUCTANCE REDUCTION FROM INITIAL VALUE.
- 6. Irms MEANS THAT MAX DC CURRENT WILL CAUSE PROXIMATELY 40°C TEMPERATURE RISE FROM 25±5°C AMBIENT.

	DIMENSIONS ARE IN mm.			This print is the property of Loir Tech. and is loaned in confidence subject to return upon request o with the understanding that no copies shall be made without the written consent of Laird Tech. Al rights to design or invention are reserved.	e and e II	Laird			5
				PROJECT/PART NUMBER:	T	EV	PART TY	PE:	DRAWN BY:
				MGV2520122R2M-10		Α		OKE ICTOR	QIU
				DATE: 06/08/17	SCAL	E: N	TS	SHEET:	
Α	ORGINAL	06/08/17	QIU		TOOL				
REV	DESCRIPTION	DATE	INT			_		1	of 1